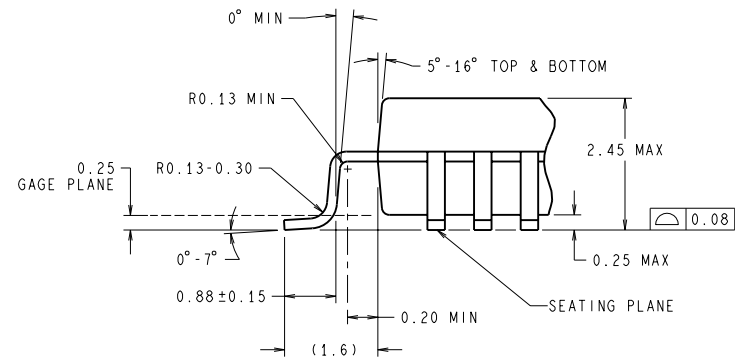
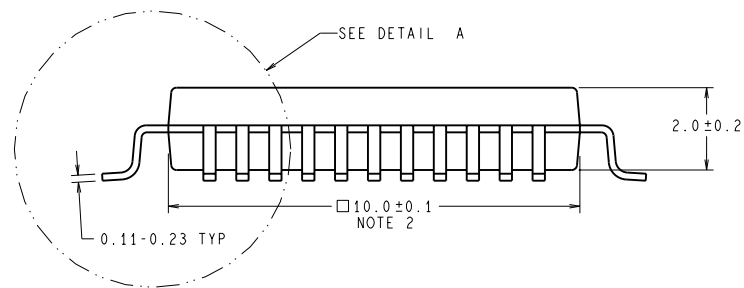
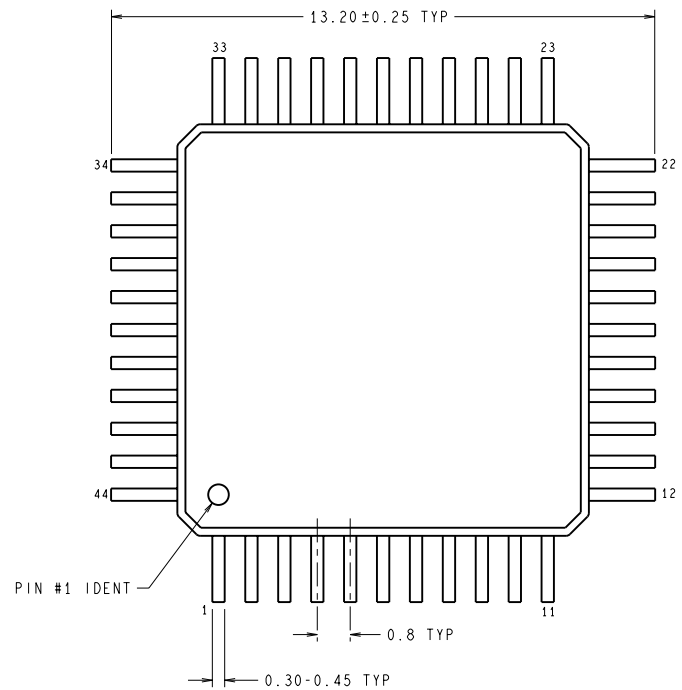


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
B	REVISE AND REDRAW PER JEDEC MS-022.	11032	07/12/95	DEG/



DETAIL A
TYP, SCALE: 17X

DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.25mm PER SIDE.
- REFERENCE JEDEC STANDARD MS-022, VARIATION AB,
DATED FEB/95.

APPROVALS	DATE	National Semiconductor		
DRAWN <i>D. E. Grady</i>	07/12/95	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK.		PQFP, JEDEC METRIC, (S), 10 X 10 X 2.0mm, 44 LEAD		
ENGR. CHK.				
		SCALE N/A	SIZE C	DRAWING NUMBER MKT-VEK44A
		DO NOT SCALE DRAWING		REV B
				SHEET 1 of 1